

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2590933

SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Ching-Ling Lin</td> <td>09/10/2013</td> </tr> <tr> <td>Chih-Sen Huang</td> <td>10/18/2013</td> </tr> <tr> <td>Po-Chao Tsao</td> <td>10/18/2013</td> </tr> <tr> <td>Ching-Wen Hung</td> <td>10/18/2013</td> </tr> <tr> <td>Jia-Rong Wu</td> <td>09/10/2013</td> </tr> <tr> <td>Chien-Ting Lin</td> <td>10/18/2013</td> </tr> </tbody> </table>		Name	Execution Date	Ching-Ling Lin	09/10/2013	Chih-Sen Huang	10/18/2013	Po-Chao Tsao	10/18/2013	Ching-Wen Hung	10/18/2013	Jia-Rong Wu	09/10/2013	Chien-Ting Lin	10/18/2013
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RECEIVING PARTY DATA															
Name:	UNITED MICROELECTRONICS CORP.														
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park														
City:	Hsin-Chu City														
State/Country:	TAIWAN														
PROPERTY NUMBERS Total: 1															
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14062909</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14062909										
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Application Number:	14062909														
CORRESPONDENCE DATA															
Fax Number:	(703)997-4517														
Phone:	3027291562														
Email:	Patent.admin.uspto.cr@naipo.com														
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>															
Correspondent Name:	WINSTON HSU														
Address Line 1:	P.O.BOX 506														
Address Line 4:	MERRIFIELD, VIRGINIA 22116														
ATTORNEY DOCKET NUMBER:	NAUP1992USA														
NAME OF SUBMITTER:	SHELLEY KUO														

Signature:	/SHELLEY KUO/
Date:	10/25/2013
Total Attachments: 12 source=1780214#page1.tif source=1780214#page2.tif source=1780214#page3.tif source=1780214#page4.tif source=1780214#page5.tif source=1780214#page6.tif source=1780214#page7.tif source=1780214#page8.tif source=1780214#page9.tif source=1780214#page10.tif source=1780214#page11.tif source=1780214#page12.tif	

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

**Title of Invention:
METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE**

As the below named inventor, I hereby declare that:
This declaration is directed to:

- The attached application, or
- United States application number _____ filed on _____, or
- PCT international application number _____ filed on _____

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

In consideration of the payment by **UNITED MICROELECTRONICS CORP.** having a postal address of _____

No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.

(referred to as "ASSIGNEE" below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.

I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal

representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, I have hereunto set hand and seal this SEP 10 2013 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Ching-Ling Lin

Date: 2013.9.10.

Signature: Ching-Ling Lin

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IN WITNESS WHEREOF, I have hereunto set hand and seal this OCT 18 2013 (Date of signing)

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chih-Sen Huang**

Date: **OCT 18 2013**

Signature: Chih-Sen Huang

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Po-Chao Tsao

Date: OCT 18 2013

Signature: Po-Chao Tsao

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Ching-Wen Hung

Date:

OCT 18 2013

Signature:

Ching-Wen Hung

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Docket No NAUP1992USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Jia-Rong Wu

Date: 2013.08.10

Signature: Jia-Rong Wu

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Docket No NAUP1992USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Chien-Ting Lin

Date:

OCT 18 2013

Signature:

Chien Ting Lin

NPO#NAU-P1992-USA:0
CUST#UMCD-2013-0276

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F#NPO-P0002E-US1201
DSC0-102U008977

RECORDED: 10/25/2013

PATENT
REEL: 031474 FRAME: 0802